

ABSTRACT

Systems and methodologies are provided for fabrication of a self contained keypad module having a top cover and a bottom cover. The top cover and the bottom cover encapsulate and/or sandwich a stack of keypad components *via* an over mold procedure that is performed around the stack. The packed stack between the top cover and the bottom cover can include a flex member, an electro luminous panel, and a silicone membrane with a plurality of keys thereupon.